

**In Th Specification**

At page 1 before the "Technical Field" section, please insert the following:

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**--RELATED PATENT DATA**

A2 This patent resulted from a divisional application of U.S. Patent Application Serial No. 09/449,025, filed November 24, 1999, entitled "Physical Vapor Deposition Targets, Conductive Integrated Circuit Metal Alloy Interconnects, Electroplating Anodes, and Metal Alloys For Use as a Conductive Interconnection in an Integrated Circuit", naming Shozo Nagano, Hinrich Hargarter, Jianxing Li and Jane Buehler as inventors, the disclosure of which is incorporated by reference.--

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**In the Claims**

Cancel claims 1-30 and 34-59 without prejudice.

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